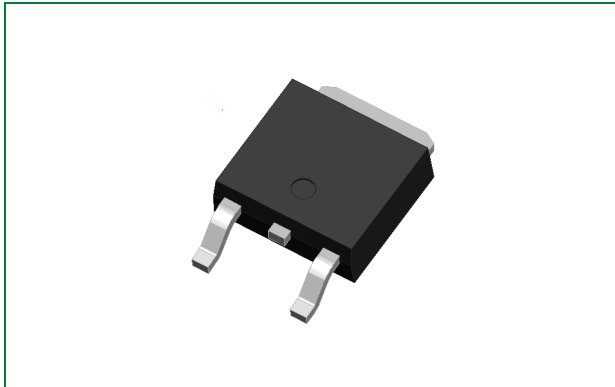


LGD8209TI
410 V, 12 A N-Channel Ignition IGBT



Product Summary

Characteristic	Value	Unit
V_{CES}	410	V
I_c	12	A

Description

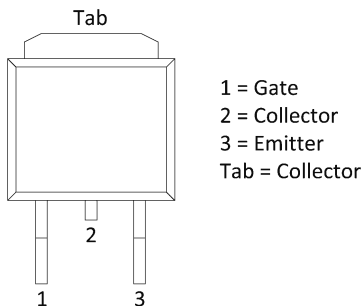
This Logic Level Insulated Gate Bipolar Transistor (IGBT) features monolithic circuitry integrating ESD and Over-Voltage clamped protection for use in inductive coil drivers applications. Primary uses include motorbike ignition, Direct Fuel Injection, or wherever high voltage and high current switching is required.

Agency Approvals and Environmental

Environmental Approvals



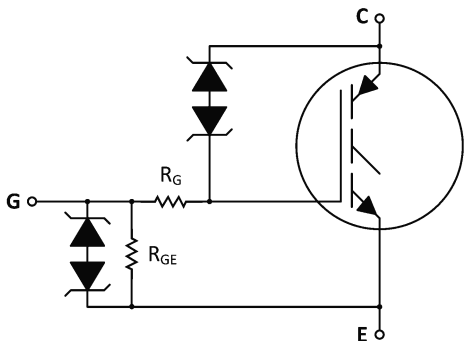
Pinout Diagram



Features

- Ideal for Coil-on-Plug Applications
- DPAK Package Offers Smaller Footprint and Increased Board Space
- Gate-Emitter ESD Protection
- Temperature Compensated Gate-Collector Voltage Clamp Limits Stress Applied to Load
- Low Saturation Voltage
- High Pulsed Current Capability
- These are Pb-Free Devices

Functional Diagram



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1. Maximum Ratings ($T_J = 25\text{ }^\circ\text{C}$ unless otherwise specified)

Characteristic	Conditions	Symbol	Value	Unit
Collector-Emitter Voltage	-	V_{CES}	445	V_{DC}
Collector-Gate Voltage	-	V_{CER}	445	V_{DC}
Gate-Emitter Voltage	-	V_{GE}	15	V_{DC}
Collector Current – Continuous		I_C	12	A_{DC}
Collector Current – Pulsed	$T_C = 25\text{ }^\circ\text{C}$		30	A_{AC}
ESD – Human Body Model	$R = 1500\ \Omega, C = 100\ \text{pF}$	ESD	8.0	kV
ESD – Machine Model	$R = 0\ \Omega, C = 200\ \text{pF}$		800	V
Total Power Dissipation	$T_C = 25\text{ }^\circ\text{C}$	P_D	94	W
	Derating for $> 25\text{ }^\circ\text{C}$		0.63	$\text{W}/^\circ\text{C}$
Operating and Storage Temperature Range	-	T_J, T_{stg}	-55 to +175	$^\circ\text{C}$

2. Unclamped Collector-to-Emitter Avalanche Characteristics

Characteristic	Symbol	Value	Unit
Single Pulse Collector-to-Emitter Avalanche Energy			
$V_{CC} = 50\text{ V}, V_{GE} = 5.0\text{ V}, P_{kL} = 7.4\text{ A}, L = 10\text{ mH}, \text{Starting } T_J = 25\text{ }^\circ\text{C}$	E_{AS}	274	mJ

3. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$	1.6	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction to Ambient (DPAK) ¹	$R_{\theta JA}$	105	$^\circ\text{C}/\text{W}$
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 5 seconds	T_L	275	$^\circ\text{C}$

Footnote 1: When surface mounted to an FR4 board using the minimum recommended pad size

4. Electrical Characteristics – Off

Characteristic	Symbol	Conditions	Temperature	Value			Unit
				Min	Typ	Max	
Collector-Emitter Clamp Voltage	BV_{CES}	$I_C = 2.0 \text{ mA}$	$T_J = -40 \text{ }^\circ\text{C to } 150 \text{ }^\circ\text{C}$	380	410	435	V_{DC}
		$I_C = 10 \text{ mA}$		340	420	445	
Zero Gate Voltage Collector Current	I_{CES}	$V_{CE} = 350 \text{ V}, V_{GE} = 0 \text{ V}$	$T_J = 25 \text{ }^\circ\text{C}$	-	1.0	25	μA_{DC}
			$T_J = 150 \text{ }^\circ\text{C}$	-	9.0	50	
			$T_J = -40 \text{ }^\circ\text{C}$	-	0.5	15	
Reverse Collector-Emitter Leakage Current	I_{ECS}	$V_{CE} = -24 \text{ V}$	$T_J = 25 \text{ }^\circ\text{C}$	-	0.5	1.0	mA
			$T_J = 150 \text{ }^\circ\text{C}$	-	10	30	
			$T_J = -40 \text{ }^\circ\text{C}$	-	0.05	0.5	
Reverse Collector-Emitter Clamp Voltage	$BV_{CES(R)}$	$I_C = -75 \text{ mA}$	$T_J = 25 \text{ }^\circ\text{C}$	26	33	38	V_{DC}
			$T_J = 150 \text{ }^\circ\text{C}$	29	36	41	
			$T_J = -40 \text{ }^\circ\text{C}$	24	32	36	
Gate-Emitter Clamp Voltage	BV_{GES}	$I_G = 5.0 \text{ mA}$	$T_J = -40 \text{ }^\circ\text{C to } 150 \text{ }^\circ\text{C}$	10	13	16	V_{DC}
Gate-Emitter Leakage Current	I_{GES}	$V_{GE} = 10 \text{ V}$	$T_J = -40 \text{ }^\circ\text{C to } 150 \text{ }^\circ\text{C}$	380	635	1000	μA_{DC}
Gate Resistor	R_G	-	$T_J = -40 \text{ }^\circ\text{C to } 150 \text{ }^\circ\text{C}$	-	70	-	Ω
Gate-Emitter Resistor	R_{GE}	-	$T_J = -40 \text{ }^\circ\text{C to } 150 \text{ }^\circ\text{C}$	10	16	26	k Ω

5. Electrical Characteristics – On

Characteristic	Symbol	Conditions	Temperature	Value			Unit
				Min	Typ	Max	
Gate Threshold Voltage	$V_{GE(th)}$	$I_C = 1.0 \text{ mA}, V_{GE} = V_{CE}$	$T_J = 25 \text{ }^\circ\text{C}$	1.0	1.42	2.0	V_{DC}
			$T_J = 150 \text{ }^\circ\text{C}$	0.7	0.95	1.5	
			$T_J = -40 \text{ }^\circ\text{C}$	1.1	1.62	2.2	
Threshold Temperature Coefficient (Negative)	-	-	-	-	3.5	-	mV/ $^\circ\text{C}$
Collector-Emitter On-Voltage ²	$V_{CE(on)}$	$I_C = 6.0 \text{ A}, V_{GE} = 4.0 \text{ V}$	$T_J = 25 \text{ }^\circ\text{C}$	0.8	1.45	2.0	V_{DC}
			$T_J = 150 \text{ }^\circ\text{C}$	0.85	1.44	1.85	
			$T_J = -40 \text{ }^\circ\text{C}$	1.0	1.5	1.95	
		$I_C = 10 \text{ A}, V_{GE} = 4.5 \text{ V}$	$T_J = 25 \text{ }^\circ\text{C}$	1.1	1.79	2.3	
			$T_J = 150 \text{ }^\circ\text{C}$	1.2	1.9	2.2	
			$T_J = -40 \text{ }^\circ\text{C}$	1.3	1.77	2.2	
Forward Transconductance	gfs	$V_{CE} = 5.0 \text{ V}, I_C = 6.0 \text{ A}$	$T_J = -40 \text{ }^\circ\text{C to } 150 \text{ }^\circ\text{C}$	5.0	14	30	Mhos

Footnote 2: Pulse Test: Pulse Width $\leq 300 \mu\text{s}$, Duty Cycle $\leq 2\%$

6. Figure Data

Figure 1. Output Characteristics ($T_J = 25\text{ }^\circ\text{C}$)

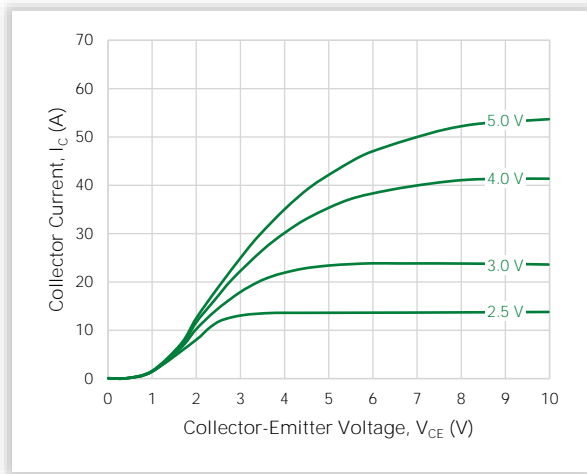


Figure 2. Output Characteristics ($T_J = -40\text{ }^\circ\text{C}$)

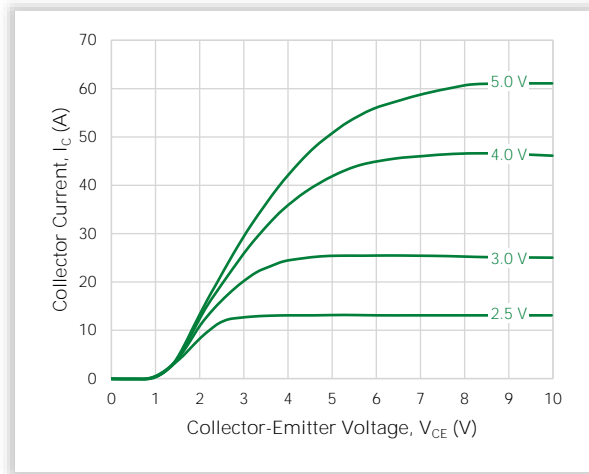


Figure 3. Output Characteristics ($T_J = 150\text{ }^\circ\text{C}$)

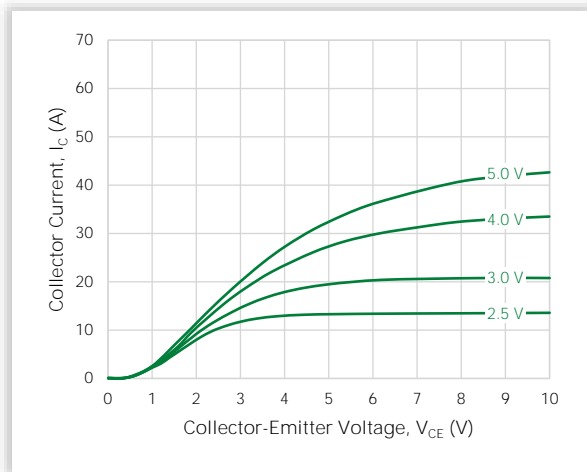


Figure 4. Transfer Characteristics

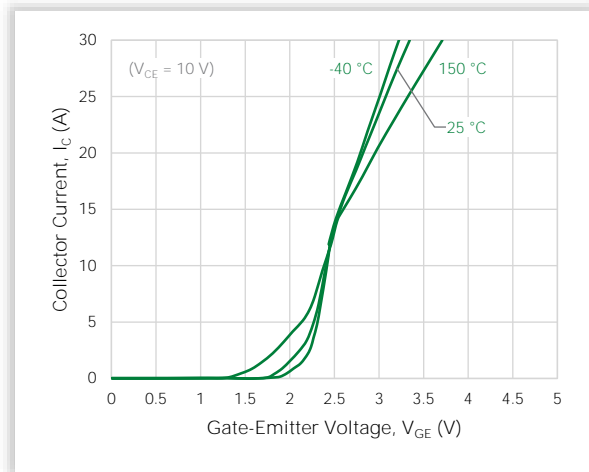


Figure 5. Collector-to-Emitter Saturation Voltage vs. Junction Temperature

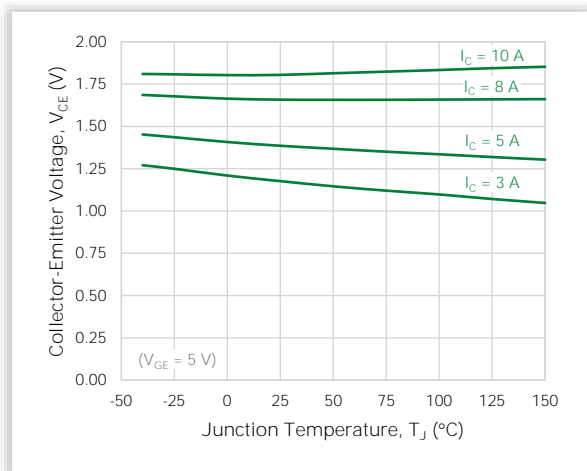


Figure 6. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage

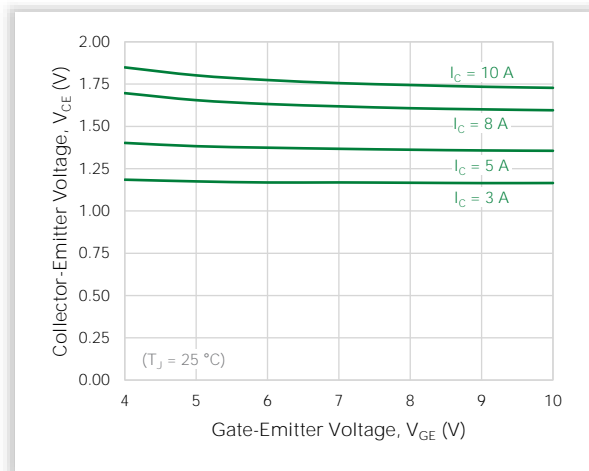


Figure 7. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage

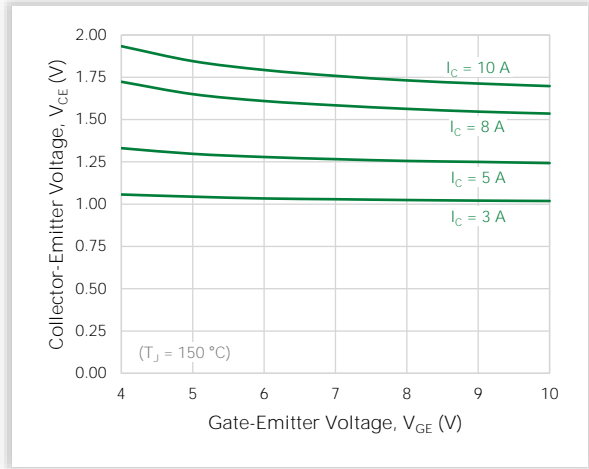
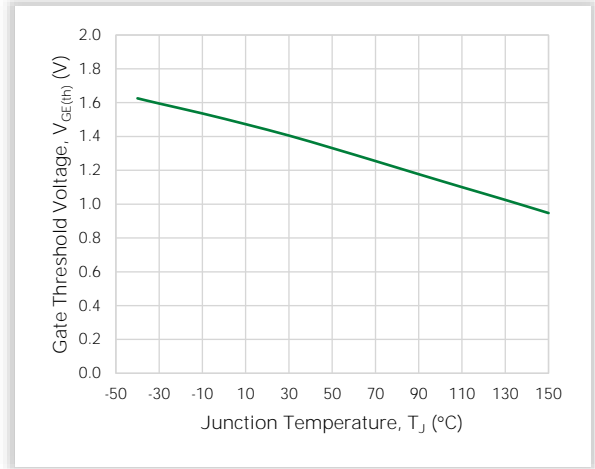
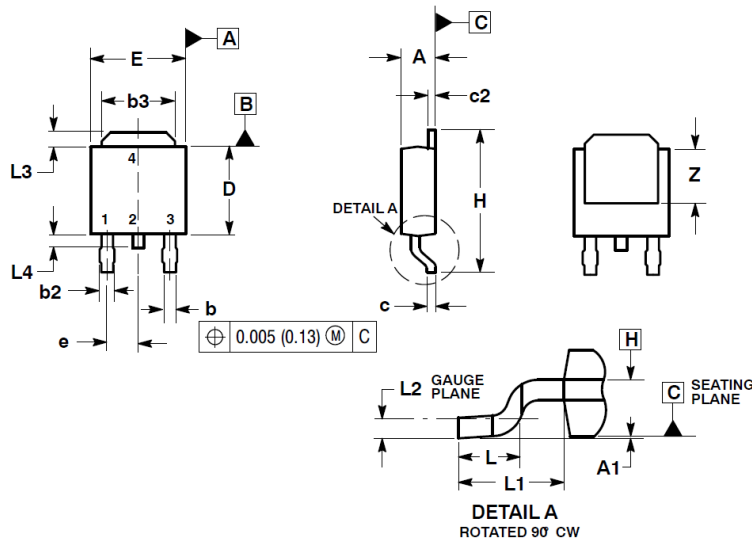


Figure 8. Gate Threshold Voltage vs. Junction Temperature

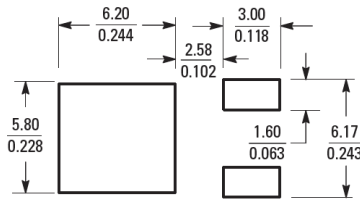


7. Package Dimensions



Symbol	Millimeters		
	Min	Nom	Max
A	2.18	-	2.38
A1	0.00	-	0.13
b	0.63	-	0.89
b2	0.76	-	1.14
b3	4.57	-	5.46
c	0.46	-	0.61
c2	0.46	-	0.61
D	5.97	-	6.22
E	6.35	-	6.73
e	2.29 BSC		
H	9.40	-	10.41
L	1.40	-	1.78
L1	2.74 REF		
L2	0.51 BSC		
L3	0.89	-	1.27
L4	-	-	1.01
Z	3.93	-	-

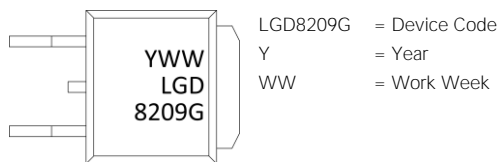
Recommended Solder Pad Layout:



Notes:

1. Dimensioning and tolerancing per ASME Y14.5M, 1994.
2. Controlling dimension: Inches.
3. Thermal pad contour optional within dimensions b3, L3, and Z.
4. Dimensions D and E do note include mild flash, protrusions, or burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 inches per side.
5. Dimensions D and E are determined at the outermost extremes of the plastic body.
6. Datums A and B are determined at datum plane H.

8. Part Numbering and Marking



9. Packing Options

Part Number	Package	Packing Mode	M.O.Q.
LGD8209TI	DPAK (Pb-Free)	Tape & Reel	2500

For additional information please visit www.Littelfuse.com/powersemi

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